



产品承认书

SPECIFICATION FOR APPROVAL

客户名称:

CUSTOMER

我司料号:

OUR PART NO.

XRCM1006C-251YT

我司品名:

OUR PART NAME

Common-Mode Filter

送样日期:

DATE SAMPLES

数量:

QUANTITY

制造确认 MANUFACTURER APPROVE

拟制 DRAWN	审核 CHECKED	确认 APPROVED
Hu Fangting	RaoPing	ZhongCuilan

客户确认 CUSTOMER APPROVE

客户名称 CUSTOMER NAME:

客户料号 CUSTOMER P/N:

XRCM1006C 250UH $\pm$ 40% 2A

规格型号 DESCRIPTION:

检查结果: ☐ 合格 ☐ 不合格

签名及盖章:

INSPECT RESULT ACCEPT REJECT

SIGNATURE AND STAMP

说明 REMARK:

如对本承认书内容有异议请提出或标记发送至我司, 本承认书在未收到异议回复时于本承认书提供一周后生效。

If you have any objection to the contents of this acknowledgment, please raise it or send the mark to us.
The acknowledgment will become effective one week after the acknowledgment is provided in the absence of any objection.

东莞市祥如电子有限公司

DONGGUAN XIANGRU ELECTRONICS CO.,LTD

Tel: 0769-86346548 Fax: 0769-86346358

Email: dgxiangru@126.com



修订记录 Revision record

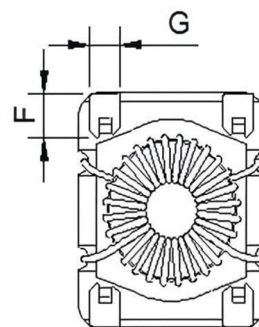
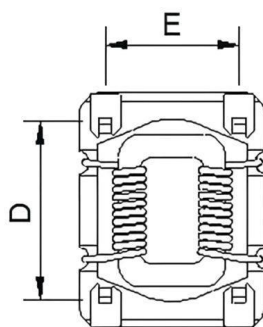
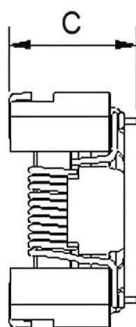
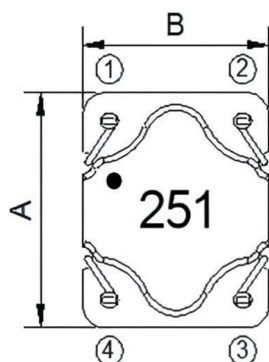
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产品承认书 SPECIFICATION FOR APPROVAL

客户名称 CUSTOMER		日期 DATE	2025/11/20
客户物料编号 CUSTOMER P/N		客户规格型号 DESCRIPTION	XRCM1006C 250UH $\pm 40\%$ 2A
我司物料编号 OUR PART NO	XRCM1006C-251YT	我司品名 OUR PART NAME	Common-Mode Filter

外观尺寸 Appearance of size

单位 Unit: mm



(121~102Y)

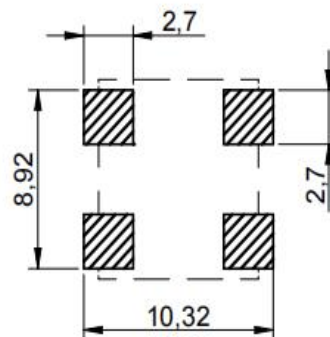
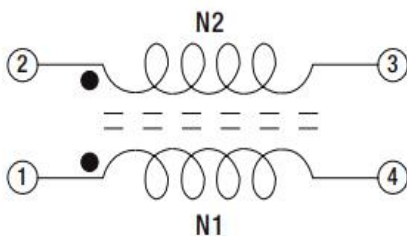
(222~472Y)

A	10.0 $\pm$ 0.3	C	6.5MAX	E	6.22 $\pm$ 0.1	G	1.4Typ
B	8.7 $\pm$ 0.3	D	7.62 $\pm$ 0.1	F	1.8Typ		
注:		Note: laser marking (激光打标)					

(以上尺寸为手工测量只做参考详细尺寸以实物为准)

电路图 Schematic Diagram:

Reference land pattern (mm)参考基板尺寸:



注意事项 Matters needing attention:



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电性参数 Electrical parameters:

Part Number 型号	Inductance (uH)电感值	LeakageInd. Inductance (uH)Typ. 漏感	D.C.R(m Ω) max. 直流电阻	RatedCurrent (A) 额定电流	RatedVolta ge(Vdc) max. 额定电压	Impedance 阻抗值	
						Frequency Range(MHz)	Min.Value (Ω)
XRCM1006C	250 $\pm 40\%$	1.5	35	2	80	5-100	400

(1).Test condition: 100KHz/0.1V,All data is tested based on 25℃ ambient temperature.

测试条件:100KHz0.1V, 所有数据都是根据25℃环境温度下测试。

(2).Impedance measure condition reference frequency range.

共模阻抗测量条件参考频率范围。

(3).Leakage inductance is for L1 and is measured with L2 shorted.

漏感:在短路L2绕组的前提下测试L1绕组所得的电感。

(4).Rated current: the value of DC current when the temperature rise is AT40℃(Ta=25℃).

额定电流:使产品温度上升到AT40℃时所加载的直流电流值(Ta=25℃)。

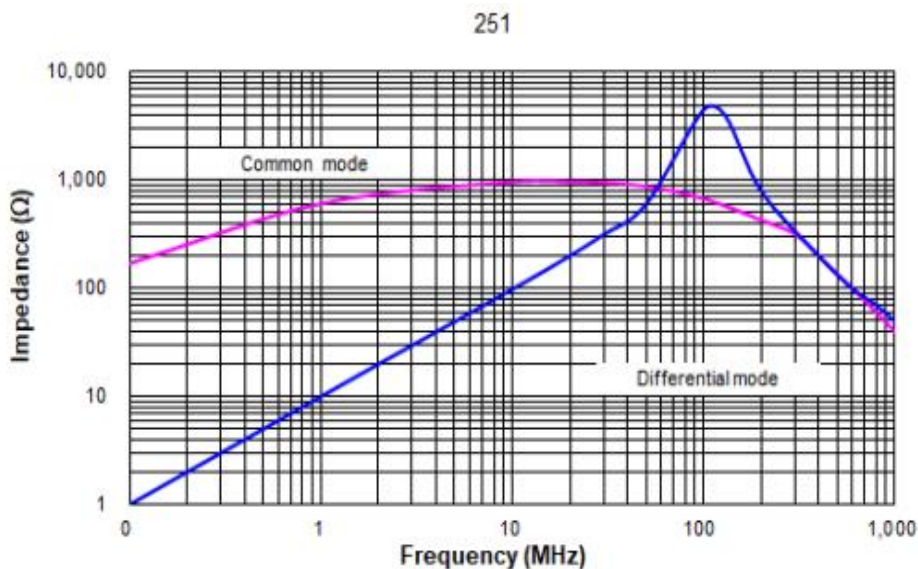
(5).Operating Temperature: -40℃ to +105℃ (Temperature rise included).

工作温度: -40℃ ~ +105℃ (包括温升)。

(6).Storage condition: Temperature 5 to 40℃, RH $\leq 70\%$.

储存条件: 温度5~40℃, 相对湿度小于等于 $\leq 70\%$ 。

Impedance vs Frequency Curve (阻抗值 VS 频率曲线):



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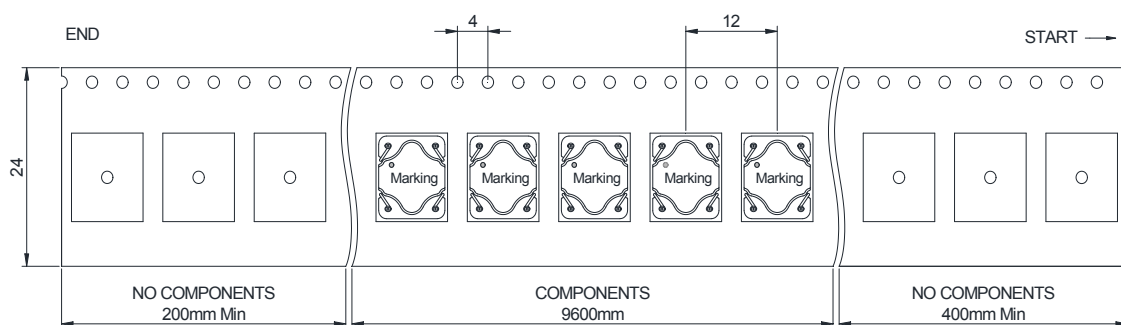
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Material list (材料清单):

No.编号	ITEM项目	DESCRIPTION描述	
1	CORE	FERRITE	
2	CASE	LCP E4008&C5191	
3	WIRE	P180 G1	
4	ADHESIVE	FH-3614	
5	TIN	Sn100%	

Packing Specification 包装规格:

(1).Tape Direction (mm)编带方向:



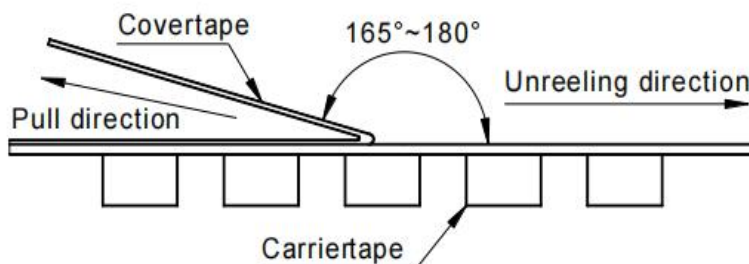
(2).Cover Tape Peel Off Condition 盖带剥离条件:

■Cover tape peel force shall be 10g to 130g.

盖带剥离力度为10~130克

■Reference peel speed 300 $\pm$ 10mm/min.

参考剥离速度为300 $\pm$ 10mm/分钟

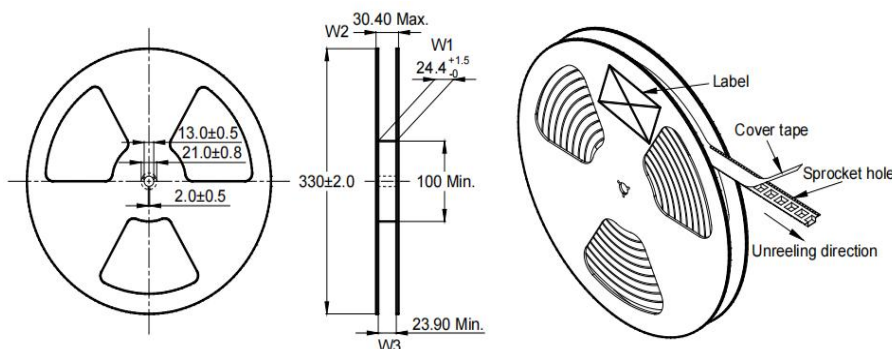


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(3). Reel Dimensions (mm) 卷盘尺寸 (mm):



(4). Carton Dimensions and Packing Quantity 包装箱尺寸和包装数量:

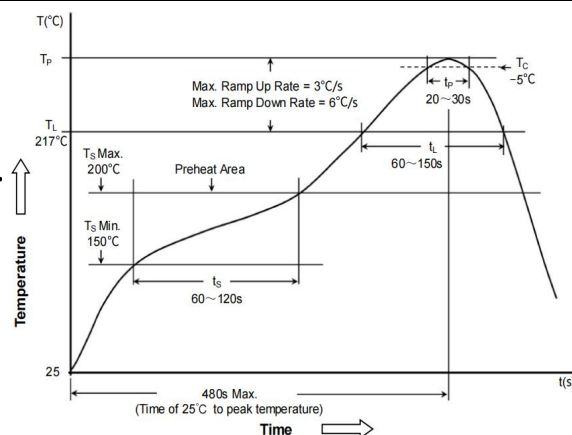
Carton:	Product Series	Quantity / Reel	Inner Carton Quantity	Out Carton Quantity
	XRCM1006C	800pcs	(800x2) = 1600pcs	(1600x3) = 4800pcs
Inner : 340x340x70mm 内包装盒		Out Carton: 360x360x240mm 外包装箱		

8. Soldering Specification 焊接规格:

(1). Reflow Profile for SMT Components

SMT 焊锡温度曲线

Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。



(2). Classification of Peak Package Body Temperature (TP) 封装体峰值温度 (TP) 分类:

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C